



Title of Change:	Final Test Capacity expansion - addition of ON Seremban, Malaysia and OSPI Tarlac, Philippines as final test locations for NCP81078MNTBG and NCP81080MNTBG	
Proposed first ship date:	1 June 2018 or earlier upon customer approval	
Contact information:	Contact your local ON Semiconductor Sales Office or <Ryan.Zhou@onsemi.com>	
Samples:	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office.	
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>	
Change Part Identification:	Customer may receive the parts from any of ON Semiconductor's facilities (Carmona, Philippines; Tarlac, Philippines; Seremban, Malaysia) from 30 May 2018 once the PCN expires or earlier depending on customer's approval. Parts tested in ON Semiconductor facilities can be identified through product packaging and labelling which follow ON Semiconductor standard.	
Change category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s): <input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____		
Sites Affected:	ON Semiconductor Sites: ON Seremban, Malaysia ON Tarlac City, Philippines	External Foundry/Subcon Sites: None
Description and Purpose: ON Semiconductor is adding two additional production test sites as shown in the table below. The purpose is to only expand test capacity and support expected increased volume. There is no change to the design, package, assembly, test coverage/flow, or datasheet.		
Change Item:	Before Change Description	After Change Description
Location	ON Semiconductor, Carmona, Philippines.	ADD both ON Semiconductor, Seremban, Malaysia, and Tarlac, Philippines.
Test equipment	Eagle ETS364, Octal site test with NX32 test board and handler.	Eagle ETS88, Dual site test with NX16 test board and handler

**Qualification Plan:**

The following is the qualification plan, expected to complete in March 2018. The scope is to perform electrical test on the new test equipment and confirm comparable results achieved to the existing test equipment:

NCP81078MNTBG				
Qualification Items/Steps	Quality Characteristic / Response to be Monitored (Input, in-process, Output)	Test /Condition	Sample Size	Accept Criteria/ Remarks
Probe, Assy, Test (Yield, GDPW, Correlation, etc.)	Test fresh lots in ETS88	Per existing spec	100%	Achieve comparable yield.
Key Parameter Electrical Distribution Comparison (Before & After & Post Stress)	10pcs correlation between ETS88 vs. ETS364	Per existing spec	100%	10/10 must correlate between 2 test platforms
Reject Bin Analysis	Rejects verification in both test platforms (ETS88 vs. ETS364)	Per existing spec	100%	Rejects must correlate between 2 test platforms
Electrical QA	Retest ETS88 FT Bin 1 in QA mode	Per existing spec	100%	100% yield

List of affected Standard Parts:

Part Number	Qualification Vehicle
NCP81078MNTBG	NCP81078MNTBG
NCP81080MNTBG	NCP81078MNTBG